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BGA Stencil for Samsung Exynos 7880 / 8895B/ 9810/ 3475/ 7580/ 8895A/ 3470/ 7570 CPU-012mm

Product ID: 22501

Price: **9.00 EUR**

Product weight: **0.20 kg**

Description:

BGA Stencil for Samsung Exynos 7880 / 8895B/ 9810/ 3475/ 7580/ 8895A/ 3470/ 7570 CPU-012mm the stencil can be heated by the hot air machine, it is easy and quickly for reballing the BGA IC. Durable in use. High success rate of planting tin.

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